TOSHIBA Field Effect Transistor Silicon N Channel MOS Type( -MOSV)

# **TPCA8010-H**

## **TENTATIVE**

## High Speed and High Efficiency DC-DC Converters

· Small footprint due to small and thin package

• High speed switching

• Small gate charge: Qg = 10nC (typ.)

• Low drain-source ON resistance: RDS (ON) = 380mO (typ.)

• High forward transfer admittance:  $|Y_{fs}| = S$  (typ.)

• Low leakage current: IDSS =  $100 \mu A \text{ (max) (VDS} = 100 \text{ V)}$ 

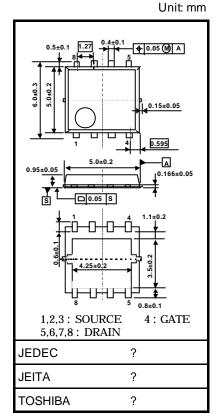
• Enhancement mode:  $V_{th} = 2 \text{ to } 4V \text{ (V DS} = 10 \text{ V, ID} = 1 \text{ mA)}$ 

## **Maximum Ratings (Ta = 25°C)**

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	200	V	
Drain-gate voltage (F	$R_{GS} = 20 \text{ k}\Omega$	$V_{DGR}$	200	V	
Gate-source voltage		$V_{GSS}$	±20	V	
Drain current	DC (Note 1)	l <sub>D</sub>	5.5	Α	
Diam current	Pulsed (Note 1)	I <sub>DP</sub>	11	A	
Drain power dissipati	on (Tc=25 )	$P_{D}$	15	W	
Drain power dissipati	on $(t = 10 s)$	$P_{D}$	2.8	W	
	(Note 2a)				
Drain power dissipati	on $(t = 10 s)$	$P_{D}$	1.6	W	
	(Note 2b)	יטי	1.0	• •	
Single pulse avalanch	ne energy (Note 3)	E <sub>AS</sub>	19	mJ	
Avalanche current		l <sub>AR</sub>	5.5	Α	
Repetitive avalanche	energy c=25 ) (Note 4)	E <sub>AR</sub>	1.5	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

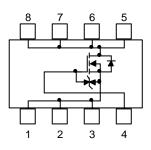
Note: For (Note 1), (Note 2), (Note 3), (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.08 g (typ.)

## **Circuit Configuration**



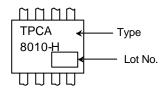


#### **Thermal Characteristics**

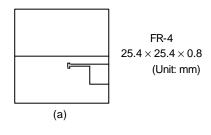
## **TENTATIVE**

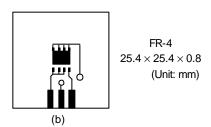
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case (Tc=25 )	R <sub>th (ch-c)</sub>	2.78	°C/W
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2a)	R <sub>th (ch-a)</sub>	44.6	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	78.1	°C/W

## Marking (Note 5)

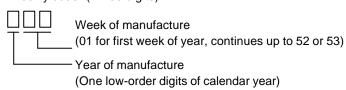


- Note 1: Please use devices on condition that the channel temperature is below 150 °C.
- Note 2: (a) Device mounted on a glass-epoxy board (a)
- (b) Device mounted on a glass-epoxy board (b)





- Note 3: V<sub>DD</sub> = 50 V , T<sub>ch</sub> = 25°C (initial) , L = 1 mH , R<sub>G</sub> = 25  $\Omega$  , I<sub>AR</sub> = 5.5 A
- Note 4: Repetitive rating: pulse width limited by max channel temperature
- Note 5: \* Weekly code: (Three digits)





# Electrical Characteristics (Ta = 25°C)

# **TENTATIVE**

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	l <sub>GSS</sub>	$V_{GS} = \pm 16  V, V_{DS} = 0  V$	± 10		μΑ	
Drain cut-OFF cu	urrent	I <sub>DSS</sub>	$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	100	μΑ
		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$ 200	_	_	V	
Drain-source bre	akdown voltage	V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -5 \text{ V}$	200	_	_	V
·		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	150	_	_	
Gate threshold v	oltage	$V_{th}$	$V_{DS} = 10 \text{ V}, I_D = 1 \text{mA}$	2.0	_	4.0	V
Drain-source ON resistance		R <sub>DS (ON)</sub>	$V_{GS} = 10 \text{ V}, I_D = 2.7\text{A}$	_	0.38	'(0.45)	mΩ
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_D = 2.7\text{A}$	TBD	TBD	_	S
Input capacitanc	e	C <sub>iss</sub>		_	600	_	
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 10  V, V_{GS} = 0  V, f = 1  MHz$	_	20	_	pF
Output capacitar	nce	C <sub>oss</sub>		_	220	_	
Output capacitance  Switching time	Rise time	t <sub>r</sub>	V <sub>GS</sub> 10 V	_	(7)		ns
	Turn-ON time	t <sub>on</sub>		_	(17)	_	
	Fall time	t <sub>f</sub>		_	(13)	_	
	Turn-OFF time	t <sub>off</sub>	$V_{DD} \simeq 100V$ Duty $\leq 1\%$ , $t_W = 10 \ \mu s$		(70)	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	(10)	_	_
Gate-source charge 1		Q <sub>gs1</sub>	$V_{DD} \approx 160 \text{ V}, V_{\odot} = 10 \text{ V}, I_D = 5.5 \text{A}$		(7.6)		nC
Gate-drain ("miller") charge		Q <sub>gd</sub>			(2.4)		
Gate switch charge		Q <sub>SW</sub>	]	_	(3.7)	_	

# **Source-Drain Ratings and Characteristics (Ta = 25°C)**

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain reverse current	Pulse	(Note 1)	I <sub>DRP</sub>	_	_	_	11	Α
Forward voltage (diode)			$V_{DSF}$	$I_{DR} = 5.5A, V_{GS} = 0 V$	_	_	-2.0	V

3 2004-3-2

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